

## Specification Sheet

### Cu Foam

(Copper Foam, Purity: 99.9%, 50PPI/1mm)

Stock No: NS6130-10-1006, CAS: 7440-50-8

<b>Product</b>	:	<b>Copper Foam</b>
Stock No	:	NS6130-10-1006
CAS	:	7440-50-8
Thickness	:	1mm
PPI	:	50
Size	:	500×500mm
Pore Size	:	1mm (50ppi)
Porosity	:	50%-98%
Molecular Formula	:	Cu
Molecular Weight	:	63.55g/mol
Density	:	8.96g/cm <sup>3</sup>
Melting Point	:	1085°C
Boiling Point	:	2562°C
Thermal Expansion	:	16.5μm.m-1.k-1
Thermal Conductivity	:	401W.m-1.k-1
Tensile Strength	:	1.25N/mm
Young's modulus	:	110-128GPa
Shear strength	:	190Psi
Vickers hardness	:	369MPa
Poisson's ratio	:	0.34
Electrical resistivity	:	1.673μΩ-cm
Specific heat	:	0.39kj/kgK
Electronegativity	:	1.90paulings
Heat of fusion	:	13.26kJ.mol-1
Heat of vaporization	:	300.4kJ.mol-1
<b>Main Inspect Verifier</b>	:	<b>Manager QC</b>

**Note:** Product Specification are subject to amendment and may change over time



## Characterization of Cu Foam



Copper Foam



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